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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16896**Generic Copy

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**Issue Date:** 15-Aug-2012

**TITLE:** Final Notification for Transfer of Zener Filtering products from Hynix (Magna Chip) in Korea to ON Semiconductor Pocatello (ID) in United State.

**PROPOSED FIRST SHIP DATE:** 15-Nov-2012 or earlier with customer approval.

**AFFECTED CHANGE CATEGORY(S):** ON Semiconductor Fab Site

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or YEW HEE SOON <[y.soon@onsemi.com](mailto:y.soon@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or Francis Lualhati  
<[francis.lualhati@onsemi.com](mailto:francis.lualhati@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

ON Semiconductor is notifying customers of its plan to transfer fabrication of Zener Filtering products from Hynix (Magna Chip) located in Seoul, South Korea, to ON Semiconductor Fab 10 located in Pocatello, ID (USA).

Description of the change:

The transfer and qualification of the Zener Z4x process and the associated integrated circuits from the Hynix (Magna Chip) facility (South Korea) to the Fab 10 wafer fabrication site located in the Pocatello, Idaho.

The Fab 10 facility is an ON Semiconductor owned wafer fab that has been producing products since 2000 (formerly as AMI). Several existing technologies within ON Semiconductor's product families are currently sourced from Fab 10, including CMOS and LVFR products. The Fab 10 Pocatello site is certified according to ISO9001:2008, 14001:2004, ISO/TS 16949:2009 and AS 9100B standards as well as MIL-PRF-38535, CTPAT and STACK.



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### RELIABILITY DATA SUMMARY:

#### Reliability Test Results:

##### CM6110:

Test:	Conditions:	Interval:	Results
HTRB	Ta = 125°C, VR = 8V	1008 hrs	0/240
HTSL	Ta = 150°C	1008 hrs	0/240
UHAST	Ta = 130°C, RH = 85%	1008 hrs	0/240
HAST	Ta = 130°C, RH = 85%, VR = 8V	192 hrs	0/240
TC	Ta = -40°C to 125°C	1000 cyc	0/240
Autoclave	Ta = 121°C, RH = 100%, 15 psig	96 hrs	0/240
ESD IEC61000-4-2, Contact Discharge	± 30KV min		± 30KV

##### CM6116

Test:	Conditions:	Interval:	Results
HTRB	Ta = 125°C, VR = 12.8V	1008 hrs	0/240
HTSL	Ta = 150°C	1008 hrs	0/240
UHAST	Ta = 130°C, RH=85%	1008 hrs	0/240
HAST	Ta = 130°C, RH=85%, VR = 12.8V	192 hrs	0/240
TC	Ta = -40°C to 125°C	1000 cyc	0/240
Autoclave	Ta = 121°C, RH = 100%, 15 psig	96 hrs	0/240
ESD IEC61000-4-2, Contact Discharge	± 30KV min		± 30KV

##### CM6136

Test:	Conditions:	Interval:	Results
UHAST	Ta = 130°C, RH=85%	1008 hrs	0/240
HAST	Ta = 130°C, RH=85%, VR = 12.8V	192 hrs	0/240
ESD IEC61000-4-2, Contact Discharge	± 30KV min		± 30KV

### ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request

### CHANGED PART IDENTIFICATION:

There will be no changes to standard device markings. Normal assembly lot traceability codes will identify the wafer fab source.

### List of affected General Parts:

CM6110  
CM6116  
CM6136  
ESD6110  
ESD6116  
ESD6136